

# PRTR5V0U8S

Integrated octal low-capacity ESD protection to IEC 61000-4-2 level 4

Rev. 01 — 14 January 2008

Preliminary data sheet

## 1. Product profile

### 1.1 General description

The PRTR5V0U8S is designed to protect Input/Output (I/O) ports that are sensitive concerning capacitive load, such as USB 2.0, Ethernet, Digital Video Interface (DVI), etc. from destruction by ElectroStatic Discharges (ESD).

Therefore, the PRTR5V0U8S incorporates eight pairs of ultra-low capacity rail-to-rail diodes plus an additional Zener diode to provide protection to downstream signal and supply components from ESD voltages as high as  $\pm 8$  kV contact discharge.

Due to the rail-to-rail diodes being connected to the Zener diode, the protection is working independent from the availability of a supply voltage.

The PRTR5V0U8S is fabricated using thin film-on-silicon technology and integrates eight pairs of ultra-low capacity rail-to-rail ESD protection diodes in a miniature 10-lead TSSOP10 package.

### 1.2 Features

- Pb-free and RoHS (Restriction of Hazardous Substances) compliant, dark green
- ESD protection of up to eight Hi-Speed data lines or high-frequency signal lines
- Eight pairs of ESD rail-to-rail protection diodes
- Ultra-low input capacitance:  $C_{(I/O-GND)} = 1$  pF
- ESD protection up to 8 kV (contact discharge compliant)
- IEC 61000-4-2, level 4 (ESD)
- Low voltage clamping due to an integrated protection Zener diode
- Small TSSOP10 (SOT552-1) package

### 1.3 Applications

- General-purpose downstream ESD protection high-frequency analog signals and high-speed serial data transmission for ports inside:
  - ◆ Cellular and Personal Communication System (PCS) mobile handsets
  - ◆ USB 2.0 ports in PC or Notebook
  - ◆ IEEE 1394 ports
  - ◆ Digital Video Interface (DVI) and High Definition Multimedia Interface (HDMI)
  - ◆ Cordless telephones
  - ◆ Wireless data: Wide Area Network (WAN) and Local Area Network (LAN) systems
  - ◆ Personal Digital Assistants (PDAs)

## 2. Pinning information

**Table 1. Pinning**

Pin	Description	Simplified outline	Symbol
1	ESD protection I/O 1		
2	ESD protection I/O 2		
3	ground (GND)		
4	ESD protection I/O 3		
5	ESD protection I/O 4		
6	ESD protection I/O 5		
7	ESD protection I/O 6		
8	supply voltage (V <sub>CC</sub> )		
9	ESD protection I/O 7		
10	ESD protection I/O 8		

*001aah386*

## 3. Ordering information

**Table 2. Ordering information**

Type number	Package		
	Name	Description	Version
PRTR5V0U8S	TSSOP10	plastic thin shrink small outline package; 10 leads; body width 3 mm	SOT552-1

## 4. Limiting values

**Table 3. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>(I/O-GND)</sub>	input/output to ground voltage		0	5.5	V
T <sub>stg</sub>	storage temperature		-55	+125	°C

**Table 4. ESD standards compliance**

Standard	Conditions
<b>Per diode</b>	
IEC 61000-4-2; level 4 (ESD)	≤ 8 kV (contact)

## 5. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T <sub>amb</sub>	ambient temperature		-40	-	+85	°C

## 6. Characteristics

Table 6. Characteristics

T<sub>amb</sub> = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Protection diodes</b>						
C <sub>(I/O-GND)</sub>	input/output to ground capacitance	V <sub>I</sub> = 0 V; f = 1 MHz; V <sub>CC</sub> = 3 V	[1] -	1.0	-	pF
I <sub>LR</sub>	reverse leakage current	V <sub>I</sub> = 3 V	[1] -	-	100	nA
<b>Zener diode</b>						
V <sub>BR</sub>	breakdown voltage	I <sub>I</sub> = 1 mA	[2] 6	-	9	V
C <sub>sup</sub>	supply pin to ground capacitance	V <sub>I</sub> = 0 V; f = 1 MHz; V <sub>CC</sub> = 3 V	[2] -	30	-	pF
V <sub>F</sub>	forward voltage		-	0.7	-	V

[1] Measured from pin 1, 2, 4, 5, 6, 7, 9 and 10 to ground

[2] Measured from pin 8 to ground

7. Package outline

TSSOP10: plastic thin shrink small outline package; 10 leads; body width 3 mm

SOT552-1

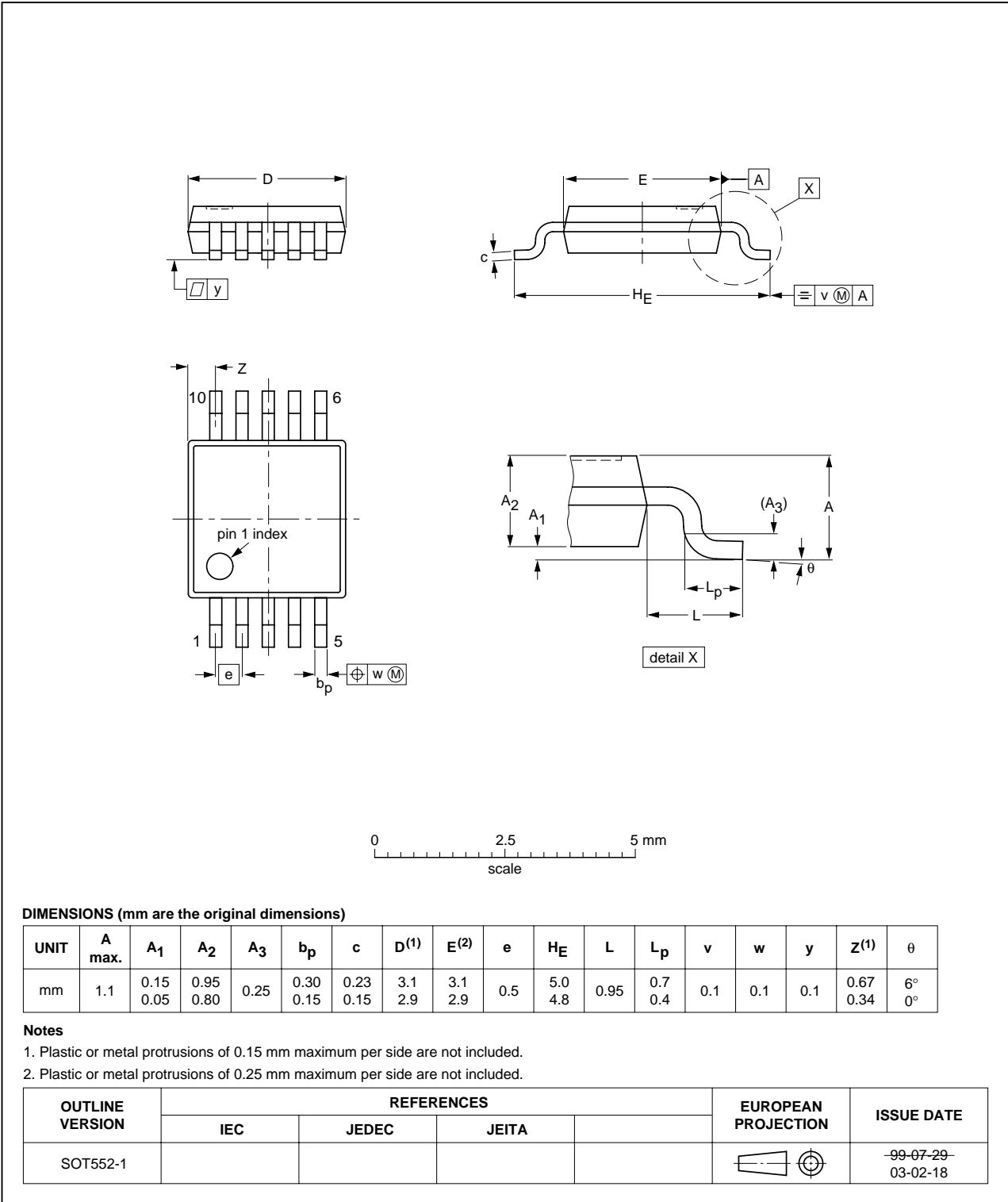


Fig 1. Package outline SOT552-1 (TSSOP10)

## 8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PRTR5V0U8S_1	20080114	Preliminary data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 14 January 2008

Document identifier: PRTR5V0U8S\_1